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June 2014

# FQPF13N50CF

## N-Channel QFET® FRFET® MOSFET

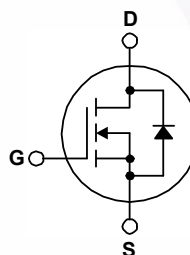
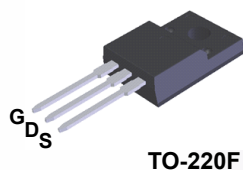
### 500 V, 13 A, 540 mΩ

#### Features

- 13 A, 500 V,  $R_{DS(on)} = 540 \text{ m}\Omega$  (Max.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 6.5 \text{ A}$
- Low Gate Charge (Typ. 43 nC)
- Low  $C_{rss}$  (Typ. 20 pF)
- 100% Avalanche Tested
- Fast Recovery Body Diode (Typ. 100 ns)

#### Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.



#### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

| Symbol         | Parameter  | FQPF13N50CF                                | Unit             |
|----------------|--|--|------------------|
| $V_{DSS}$      | Drain to Source Voltage  | 500  | V                |
| $I_D$          | Drain Current  | - Continuous ( $T_C = 25^\circ\text{C}$ )  | 13               |
|                |  | - Continuous ( $T_C = 100^\circ\text{C}$ ) | 8                |
| $I_{DM}$       | Drain Current  | 52   | A                |
|                |  | - Pulsed (Note 1)                          |                  |
| $V_{GSS}$      | Gate to Source Voltage   | $\pm 30$                                   | V                |
| $E_{AS}$       | Single Pulsed Avalanche Energy   | 530  | mJ               |
|                |  | (Note 2)                                   |                  |
| $I_{AR}$       | Avalanche Current  | 13   | A                |
|                |  | (Note 1)                                   |                  |
| $E_{AR}$       | Repetitive Avalanche Energy  | 19.5                                       | mJ               |
|                |  | (Note 1)                                   |                  |
| $dv/dt$        | Peak Diode Recovery $dv/dt$  | 4.5  | V/ns             |
|                |  | (Note 3)                                   |                  |
| $P_D$          | Power Dissipation  | ( $T_C = 25^\circ\text{C}$ )               | 48               |
|                |  | - Derate above $25^\circ\text{C}$          | 0.39             |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                                      | -55 to +150                                | $^\circ\text{C}$ |
| $T_L$          | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds | 300  | $^\circ\text{C}$ |

\*Drain current limited by maximum junction temperature

#### Thermal Characteristics

| Symbol          | Parameter                                     | FQPF13N50CF | Unit                      |
|-----------------|---|-------------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case, Max.    | 2.58        | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient, Max. | 62.5        |                           |

## Package Marking and Ordering Information

| Device Marking | Device      | Package | Reel Size | Tape Width | Quantity |
|----------------|-------------|---------|-----------|------------|----------|
| FQPF13N50CF    | FQPF13N50CF | TO-220F | Tube      | N/A        | 50 units |

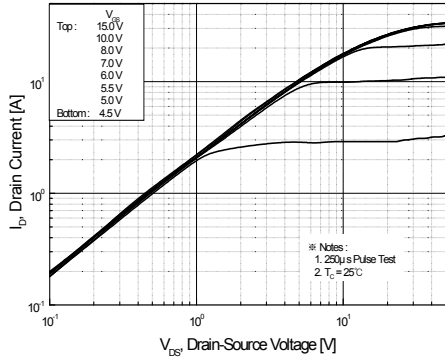
## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

| Symbol  | Parameter   | Test Conditions   | Min      | Typ  | Max  | Unit               |    |
|---|---|---|----------|------|------|--------------------|----|
| <b>Off Characteristics</b>                                    |   |   |          |      |      |                    |    |
| $BV_{DSS}$  | Drain-Source Breakdown Voltage                        | $V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$                         | 500      | --   | --   | V                  |    |
| $\Delta BV_{DSS} / \Delta T_J$                                | Breakdown Voltage Temperature Coefficient             | $I_D = 250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$           | --       | 0.5  | --   | $V/^\circ\text{C}$ |    |
| $I_{DSS}$   | Zero Gate Voltage Drain Current                       | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$                          | --       | --   | 10   | $\mu\text{A}$      |    |
|   |   | $V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$                      | --       | --   | 100  | $\mu\text{A}$      |    |
| $I_{GSSF}$  | Gate-Body Leakage Current, Forward                    | $V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$                           | --       | --   | 100  | nA                 |    |
| $I_{GSSR}$  | Gate-Body Leakage Current, Reverse                    | $V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$                          | --       | --   | -100 | nA                 |    |
| <b>On Characteristics</b>                                     |   |   |          |      |      |                    |    |
| $V_{GS(th)}$  | Gate Threshold Voltage                                | $V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$                             | 2.0      | --   | 4.0  | V                  |    |
| $R_{DS(on)}$  | Static Drain-Source On-Resistance                     | $V_{GS} = 10\text{ V}, I_D = 6.5\text{ A}$                            | --       | 0.43 | 0.54 | $\Omega$           |    |
| $g_{FS}$  | Forward Transconductance                              | $V_{DS} = 40\text{ V}, I_D = 6.5\text{ A}$                            | --       | 15   | --   | S                  |    |
| <b>Dynamic Characteristics</b>                                |   |   |          |      |      |                    |    |
| $C_{iss}$   | Input Capacitance                                     | $V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$<br>$f = 1.0\text{ MHz}$  | --       | 1580 | 2055 | pF                 |    |
| $C_{oss}$   | Output Capacitance                                    |   | --       | 180  | 235  | pF                 |    |
| $C_{rss}$   | Reverse Transfer Capacitance                          |   | --       | 20   | 25   | pF                 |    |
| <b>Switching Characteristics</b>                              |   |   |          |      |      |                    |    |
| $t_{d(on)}$   | Turn-On Delay Time                                    | $V_{DD} = 250\text{ V}, I_D = 13\text{ A},$<br>$R_G = 25\ \Omega$     | --       | 25   | 60   | ns                 |    |
| $t_r$   | Turn-On Rise Time                                     |   | --       | 100  | 210  | ns                 |    |
| $t_{d(off)}$  | Turn-Off Delay Time                                   |   | (Note 4) | --   | 130  | 270                | ns |
| $t_f$   | Turn-Off Fall Time                                    |   | (Note 4) | --   | 100  | 210                | ns |
| $Q_g$   | Total Gate Charge                                     | $V_{DS} = 400\text{ V}, I_D = 13\text{ A},$<br>$V_{GS} = 10\text{ V}$ | --       | 43   | 56   | nC                 |    |
| $Q_{gs}$  | Gate-Source Charge                                    |   | (Note 4) | --   | 7.5  | --                 | nC |
| $Q_{gd}$  | Gate-Drain Charge                                     |   | (Note 4) | --   | 18.5 | --                 | nC |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |   |   |          |      |      |                    |    |
| $I_S$   | Maximum Continuous Drain-Source Diode Forward Current |   | --       | --   | 13   | A                  |    |
| $I_{SM}$  | Maximum Pulsed Drain-Source Diode Forward Current     |   | --       | --   | 52   | A                  |    |
| $V_{SD}$  | Drain-Source Diode Forward Voltage                    | $V_{GS} = 0\text{ V}, I_S = 13\text{ A}$                              | --       | --   | 1.4  | V                  |    |
| $t_{rr}$  | Reverse Recovery Time                                 | $V_{GS} = 0\text{ V}, I_S = 13\text{ A},$                             | --       | 100  | 160  | ns                 |    |
| $Q_{rr}$  | Reverse Recovery Charge                               | $di_F / dt = 100\text{ A}/\mu\text{s}$                                | --       | 0.35 | --   | $\mu\text{C}$      |    |

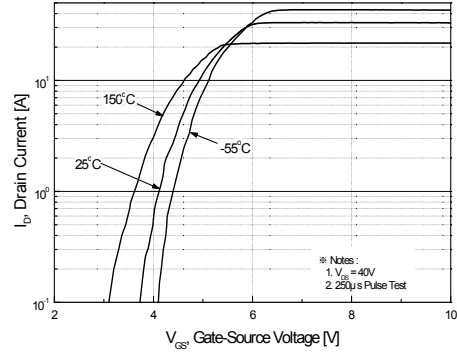
### Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2.  $L = 5.6\text{ mH}, I_{AS} = 13\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\ \Omega$ , starting  $T_J = 25^\circ\text{C}$ .
3.  $I_{SD} \leq 13\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , starting  $T_J = 25^\circ\text{C}$ .
4. Essentially independent of operating temperature.

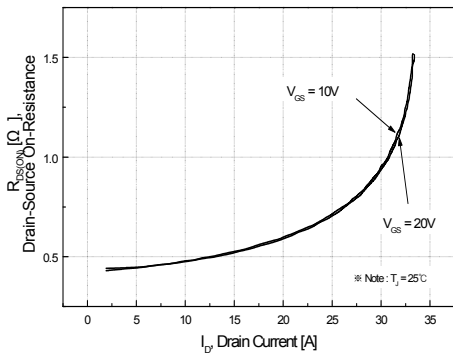
**Typical Characteristics**



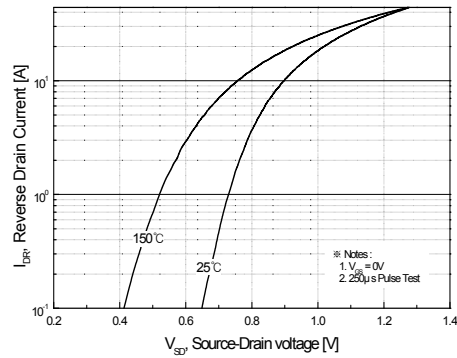
**Figure 1. On-Region Characteristics**



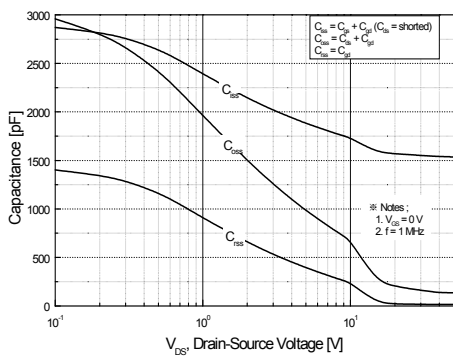
**Figure 2. Transfer Characteristics**



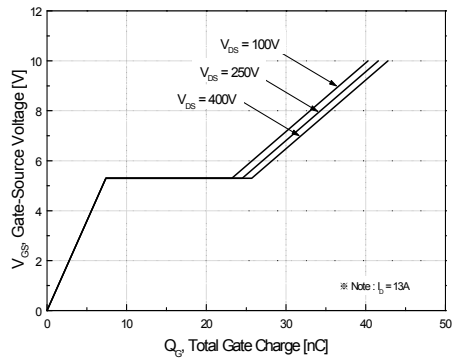
**Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

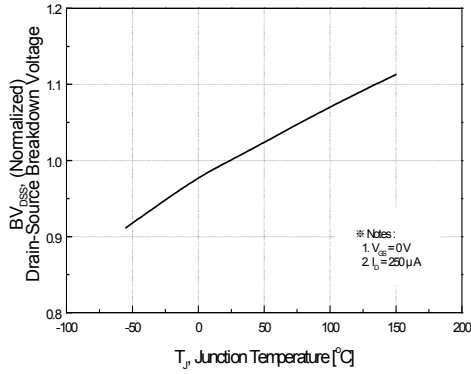


**Figure 5. Capacitance Characteristics**

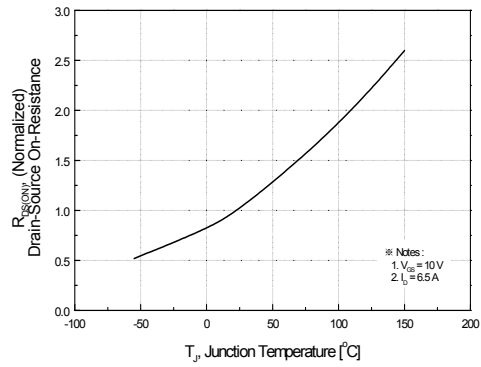


**Figure 6. Gate Charge Characteristics**

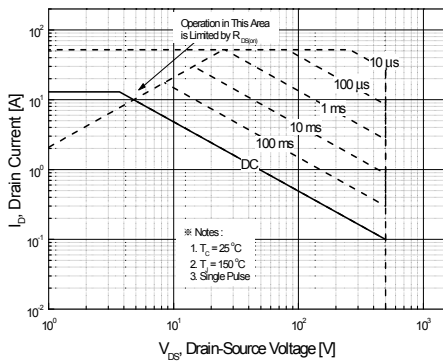
**Typical Characteristics (Continued)**



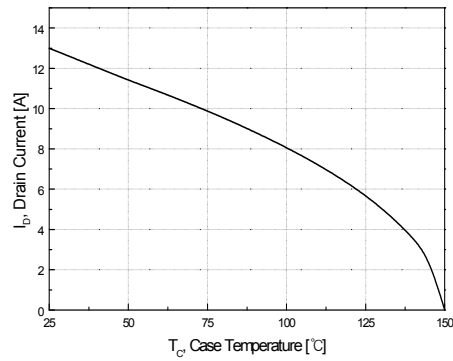
**Figure 7. Breakdown Voltage Variation vs Temperature**



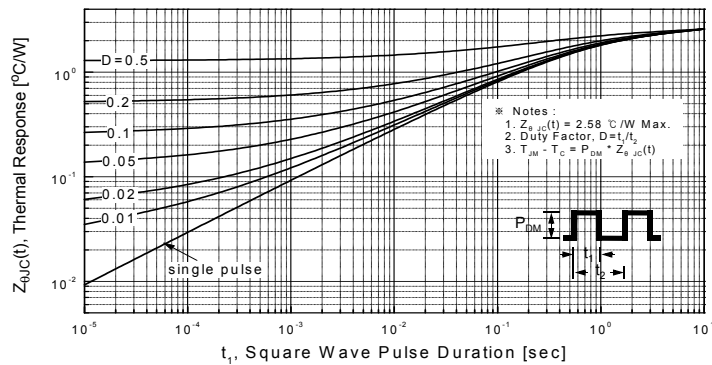
**Figure 8. On-Resistance Variation vs Temperature**



**Figure 9. Maximum Safe Operating Area**

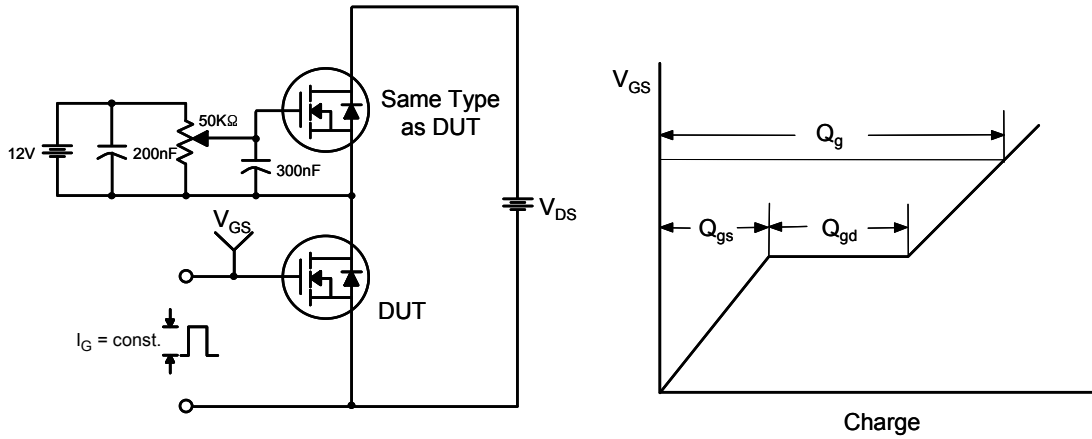


**Figure 10. Maximum Drain Current vs Case Temperature**

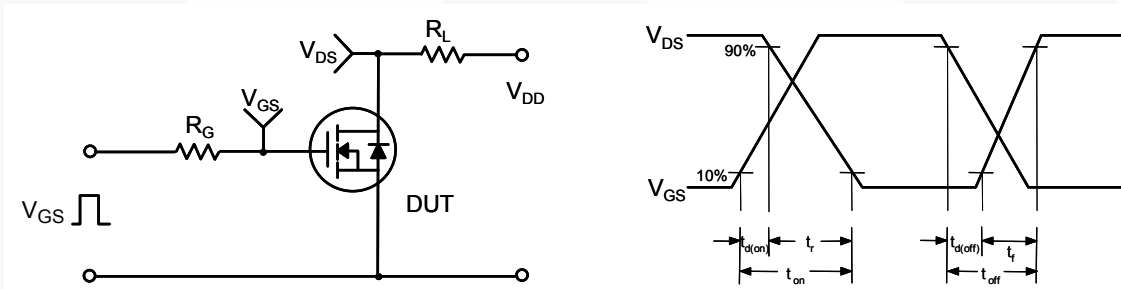


**Figure 11. Transient Thermal Response Curve**

**Figure 12. Gate Charge Test Circuit & Waveform**



**Figure 13. Resistive Switching Test Circuit & Waveforms**



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

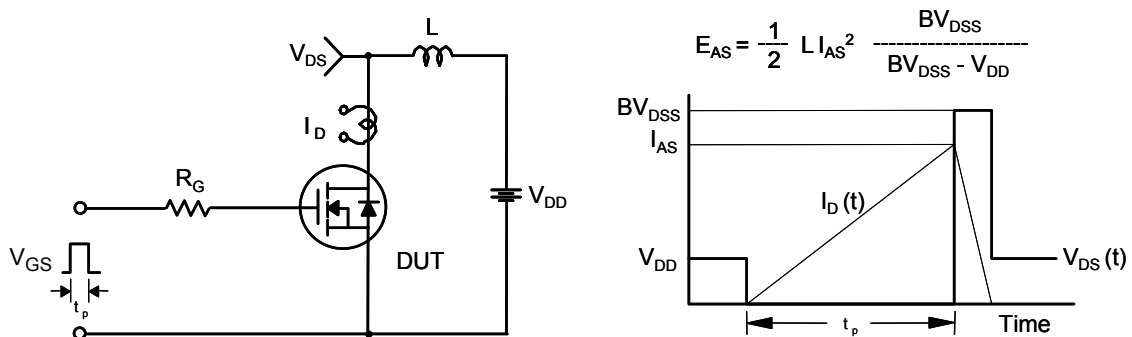
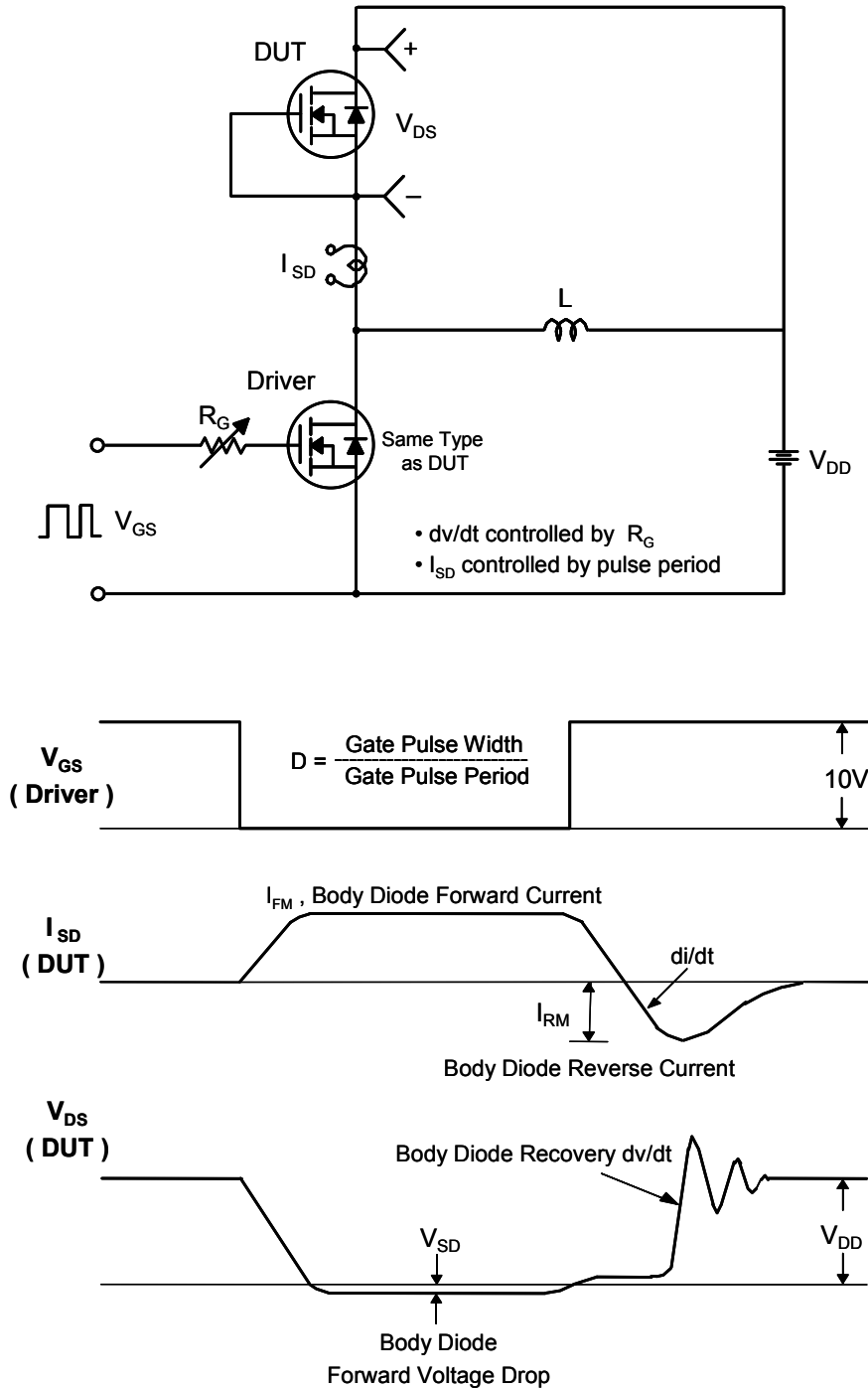
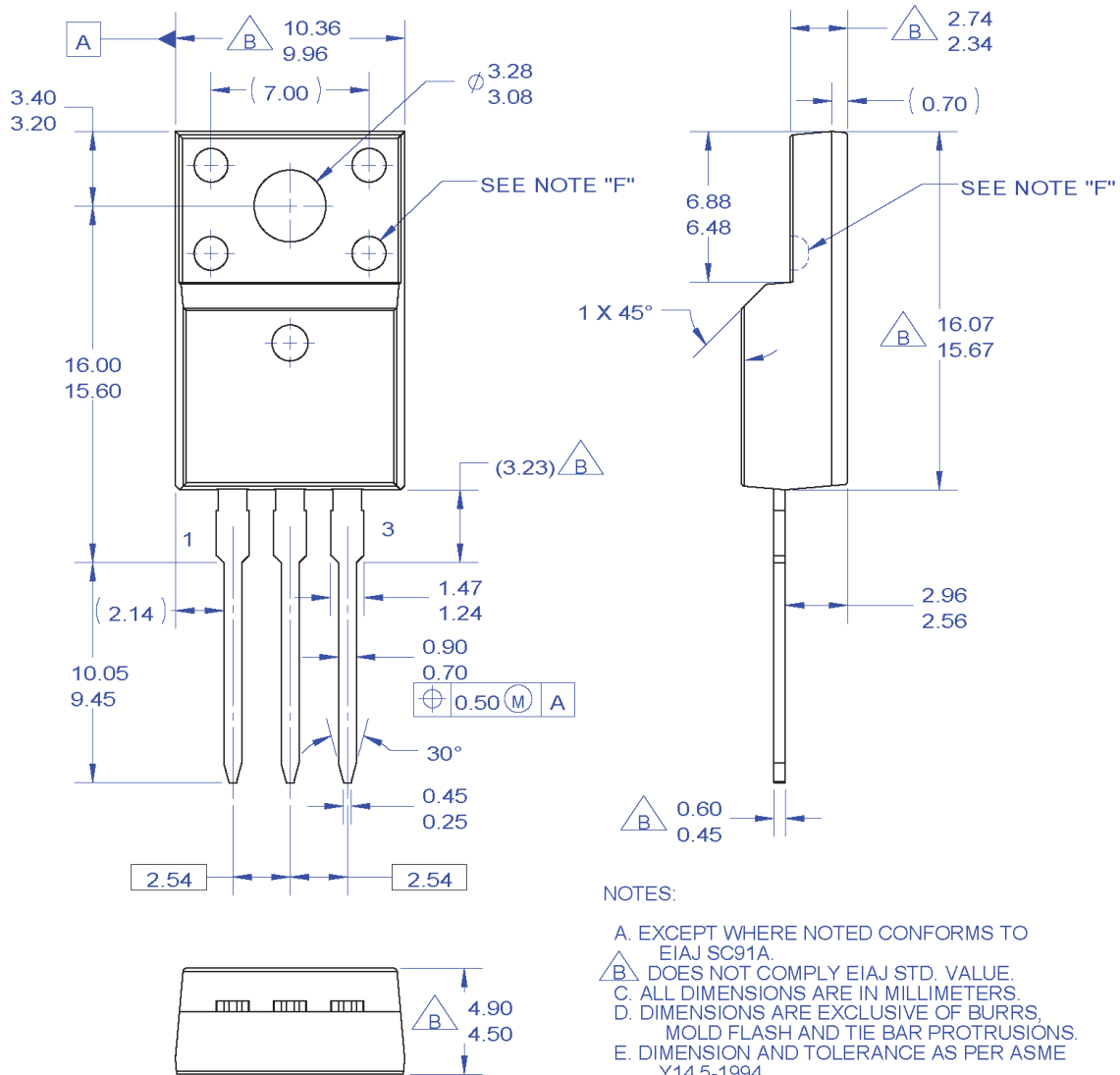


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



**Mechanical Dimensions**



**Figure 16. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead**

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